

Rad-hard current mode PWM controller



FLAT-8 metallic lid floating

Features

- Oscillator frequency guaranteed at 250 kHz
- Trimmed oscillator for precise frequency control
- Current mode operation to 500 kHz automatic feed forward compensation
- Latching PWM for cycle-by-cycle current limiting
- Internally trimmed reference with undervoltage lockout
- High current totem pole output
- Undervoltage lockout with hysteresis
- Low start-up (<0.5 mA) and operating current
- Ceramic hermetic package Flat-8 metallic lid floating
- ST1843 50 krad (Si)
- ST1845 100 krad (Si)
- SEL free @ 120 MeV/cm²/mg at 125 °C
- ESCC qualified as 9108/020 and 9108/021

Description

The **ST1843** and **ST1845** ICs are rad-hard current mode PWM controllers providing an industry standard solution for the implementation of off-line or DC to DC fixed-frequency current mode control schemes with a minimal external part count.

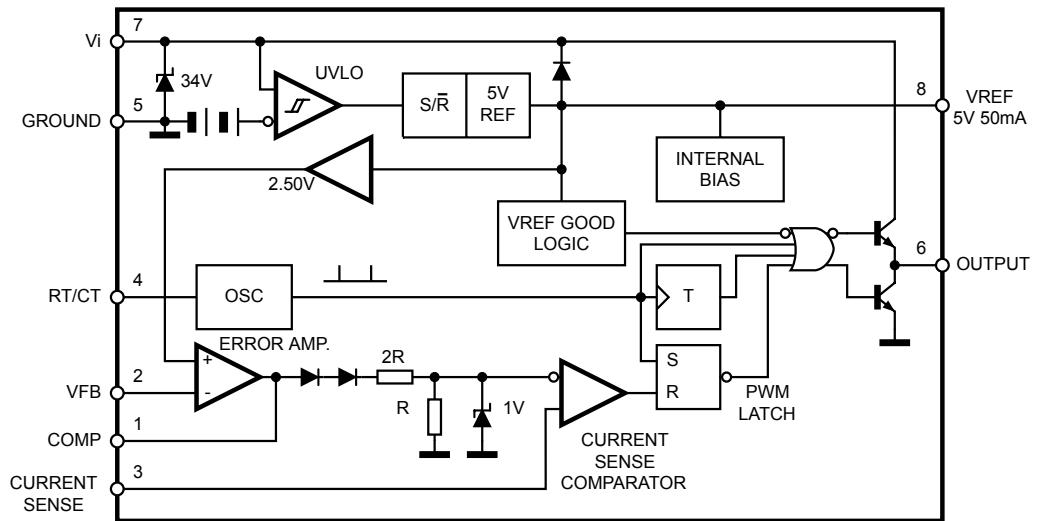
Its radiation hardness, hermetic packaging and its ESCC qualification make it an ideal choice for aerospace and other harsh environments.

Product status link

[ST1843, ST1845](#)

1 Block diagram

Figure 1. Block diagram (toggle flip-flop used in the ST1845 only)



AMG110120170900MT

2 Maximum ratings

Table 1. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_i	Supply voltage (low impedance source)	30	V
	Supply voltage ($i_i < 30 \text{ mA}$)	Self-limiting	
I_o	Output current	± 1	A
E_o	Output energy (capacitive load)	5	μJ
	Analog inputs (pins 2, 3)	-0.3 to 5.5	V
	Error amplifier output sink current	10	mA
P_{tot}	Power dissipation at $T_A \leq 25 \text{ }^\circ\text{C}$	800	mW
T_{stg}	Storage temperature range	-55 to 150	$^\circ\text{C}$
T_J	Junction operating temperature	-55 to 150	$^\circ\text{C}$

Note: All voltages are with respect to pin 5, all currents are positive into the specified terminal.

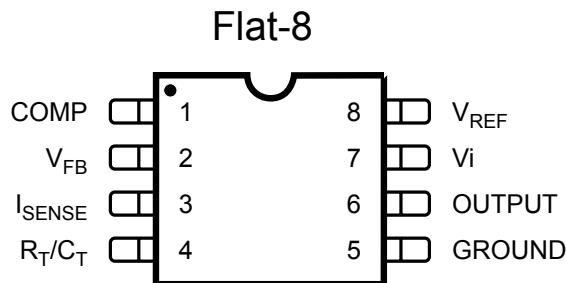
3 Thermal data

Table 2. Thermal data

Symbol	Description	Flat-8	Unit
R_{thj-a}	Thermal resistance junction-ambient conditions: 2s2p board as per std Jedec spec. JESD51-7 board size: 76.2x114.5x1.6 mm outer layers: 20% Cu inner layers: 90% Cu natural convection, $T_{AMB} = 25$ °C. 100 μ m air-gap between package and board filled in with glue ($k = 1$ W/m°K)	47.7	°C/W
$R_{thj-c\ top}$	Package top case (lid cap side) in contact with a cold plate (infinite heat sink like) as per std Jedec spec JESD51-12	20.4	
R_{thj-b}	Ring cold plate as per std Jedec spec JESD51-8	34.7	

4 Pin connection

Figure 2. Pin connection



The metallic lid is floating.

AMG110120170901MT

Table 3. Pin functions

No	Function	Description
1	COMP	This pin is the error amplifier output and is made available for loop compensation.
2	V _{FB}	This is the inverting input of the error amplifier. It is normally connected to the switching power supply output through a resistor divider.
3	I _{SENSE}	A voltage proportional to inductor current is connected to this input. The PWM uses this information to terminate the output switch conduction.
4	R _T /C _T	The oscillator frequency and maximum output duty cycle are programmed by connecting resistor RT to Vref and capacitor CT to ground. Operation to 500 kHz is possible.
5	GROUND	This pin is the combined control circuitry and power ground.
6	OUTPUT	This output directly drives the gate of a power MOSFET. Peak currents up to 1 A are sourced and sunk by this pin.
7	V _i	This pin is the positive supply of the control IC.
8	V _{ref}	This is the reference output. It provides charging current for capacitor CT through resistor RT.

6 Radiation

The technology of the STMicroelectronics rad-hard current mode PWM controller is resistant to radioactive environments.

The product radiation hardness assurance is supported by a total ionisation dose (TID) tested at low dose rate and a single effect event (SEE) characterization.

6.1 Total dose radiation (TID) testing

The ST184x are qualified, tested and characterized in full compliance with the ESCC22900 "Low Rate" window: 36 to 360 rad/h.

A characterization in total ionizing dose has been done at very low dose rate, i.e. 36 rad/h, on each device type on 5 parts biased and 5 parts unbiased.

Each wafer lot is tested at low dose rate, in the worst bias case condition, based on the results obtained during the initial qualification.

Both pre-irradiation and post-irradiation performance has been tested using the same circuitry and test conditions. A direct comparison can be done ($T_{amb} = 22 \pm 3^\circ C$ unless otherwise specified).

The following parameters were measured:

- Before irradiation
- After irradiation at final dose
- After 24 hrs at room temperature
- After 168 hrs at 100 °C anneal

Table 5. Total dose performance

Feature	Conditions	Max. value	Unit
Total-ionization dose immunity	ST1843 low dose rate. Compliance with electrical measurements for total dose radiation testing	50	krad(Si)
	ST1845 low dose rate. Compliance with electrical measurements for total dose radiation testing	100	

Unless otherwise stated, these specifications apply for $-T_A = 22 \pm 3^\circ C$, $V_i = 15 V$, adjust V_i above the start threshold before setting at 15 V; $R_T = 10 k\Omega$; $C_T = 3.3 nF$

6.2 Single event effect

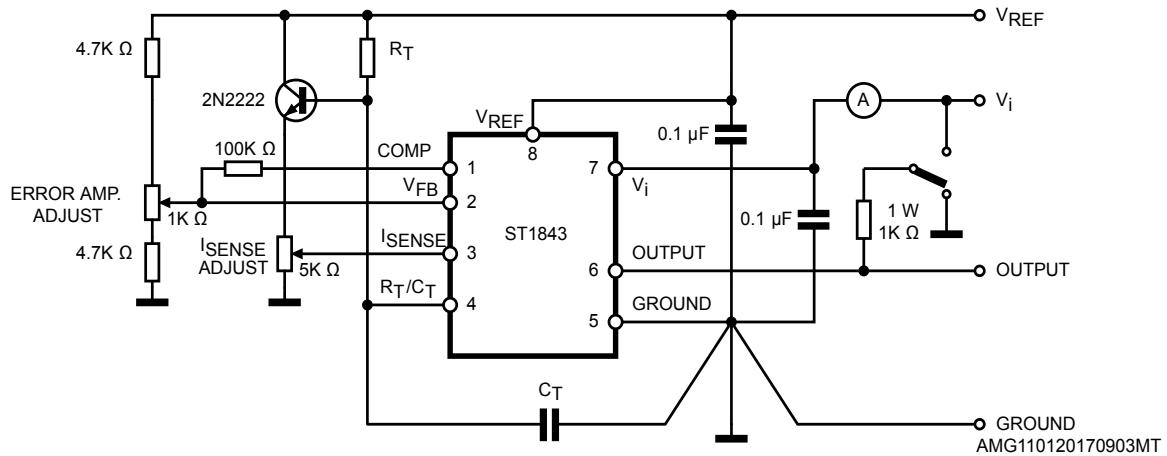
A Single event effect characterization has been performed on the qualification lots only. They have been performed according to single event effects test method ESCC basic specification number 25100. SEE tests have been characterized in RADEF (FI). The single event effect (SEE) relevant to power integrated circuits are characterized, i.e. the single event latch-up (SEL) and single event transient (SET).

The accept/reject criteria are:

- SEL: the device is biased during irradiation. Ambient temperature for the SEL test is 125 °C. The test is stopped as soon as a SEL occurs or when the consumption is above the nominal current level or when the overall fluency on the component reaches $1e^7 \text{ cm}^2$.
- SET: the device is biased during irradiation. Ambient temperature for the SET test is 25 °C. A SET is recorded when an event occurs on the output. The run is stopped when the overall fluency on the component reaches $1e^6 \text{ cm}^2$

Table 7. Radiation hardness assurance summary

Feature	Parameter	Conditions	Value	Unit
SEL immunity	Linear energy transfer (LET)	Range $\geq 40 \mu\text{m}$, $V_{IN} = 30 \text{ V}$, $T_A = +125 \text{ }^\circ\text{C}$. No destructive events	120	MeV.cm ² /mg
SET performance	Linear energy transfer threshold (LET _{th})	$V_{IN} = 15 \text{ V}$ $f^{osc} = 80 \text{ kHz}$ and 200 kHz	1.5	MeV.cm ² /mg
	ST1843 saturated cross-section		1.15 e ⁻²	cm ²
	ST1845 saturated cross-section		7.20 e ⁻³	cm ²

7
Test circuit
Figure 3. Open loop test circuit


High peak currents associated with capacitive loads necessitate careful grounding techniques. Timing and bypass capacitors should be connected close to pin 5 in a single point ground. The transistor and 5 k Ω potentiometer are used to sample the oscillator waveform and apply an adjustable ramp to pin 3.

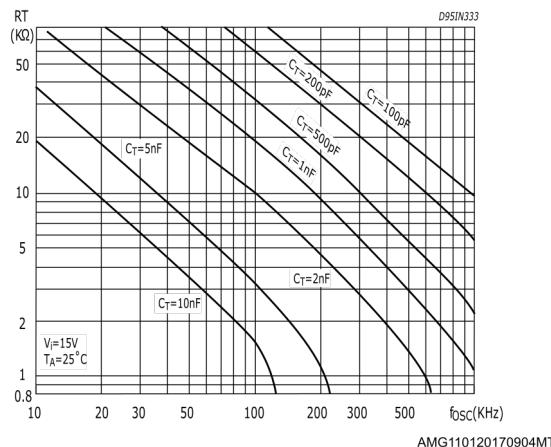
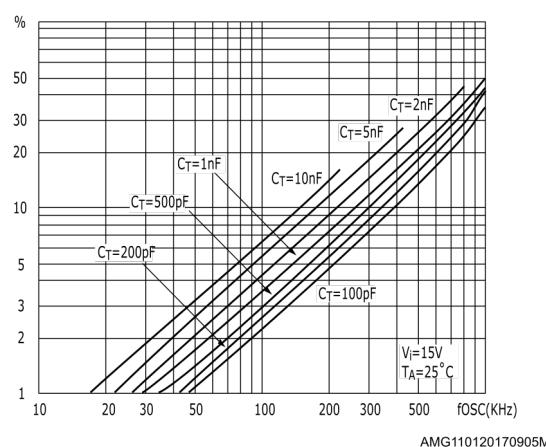
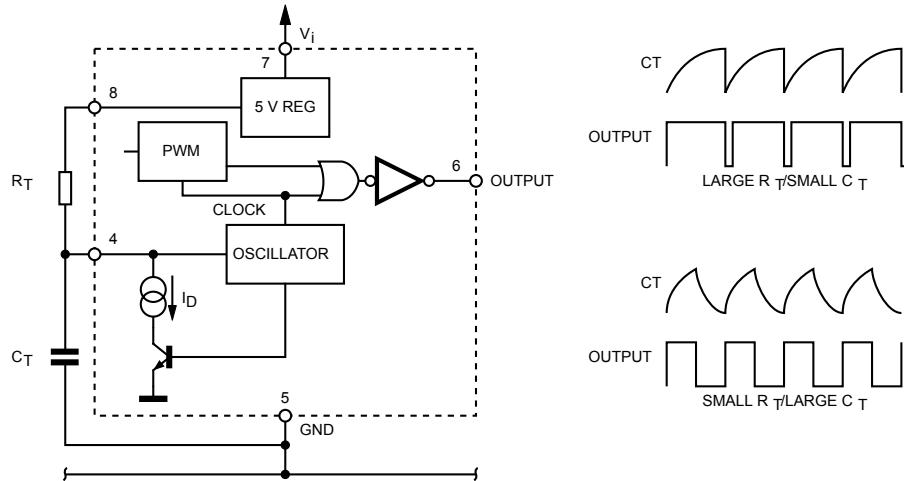
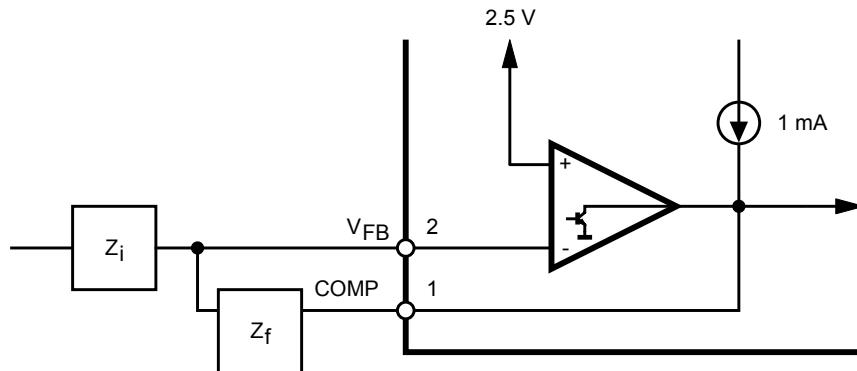
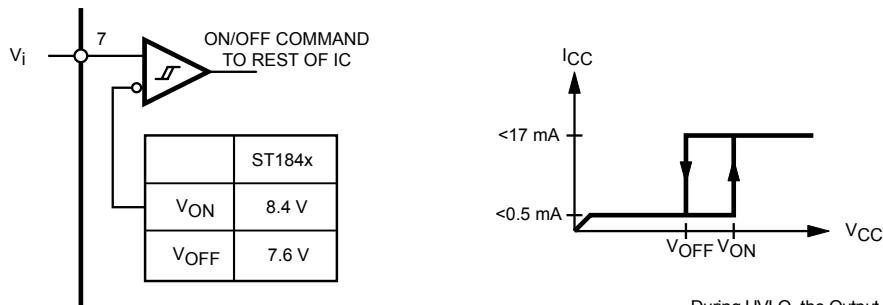
Figure 4. Timing resistor vs oscillator frequency

Figure 5. Output dead-time vs oscillator frequency


Figure 16. Oscillator and output waveforms


AMG110120170916MT

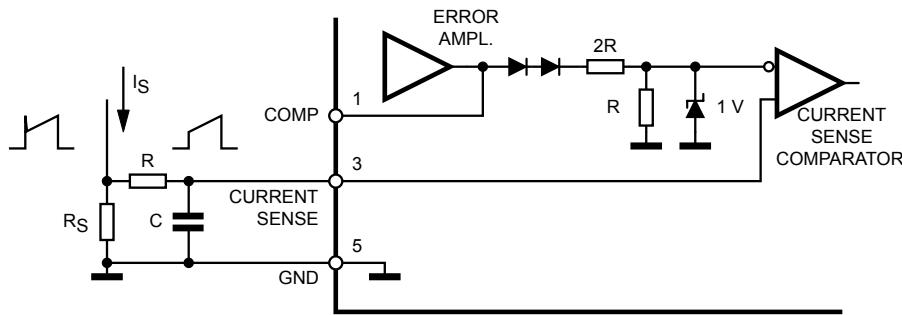
Figure 17. Error amp configuration


AMG110120170917MT

Figure 18. Undervoltage lockout


During UVLO, the Output is low

AMG110120170918MT

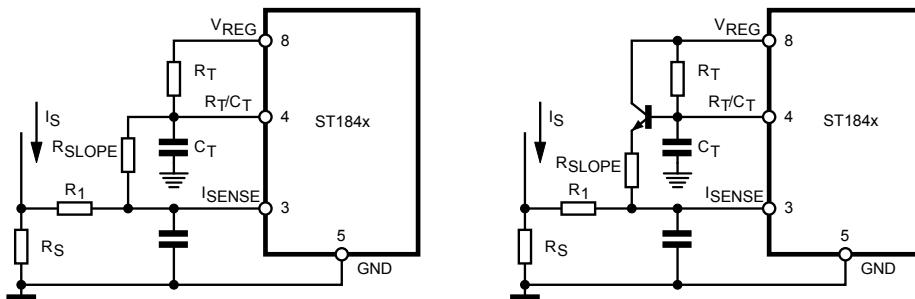
Figure 19. Current sense circuit


AMG110120170919MT

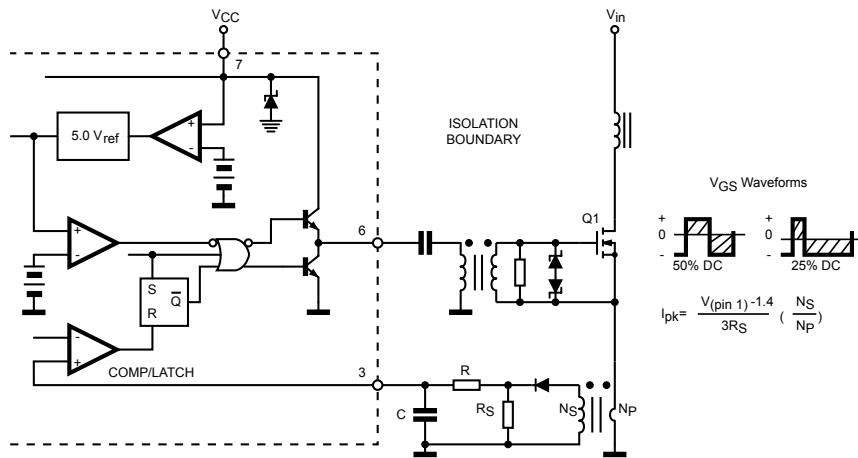
Peak current (I_{Smax}) is determined by the formula:

$$I_{Smax} \approx \frac{1.0V}{R_S} \quad (1)$$

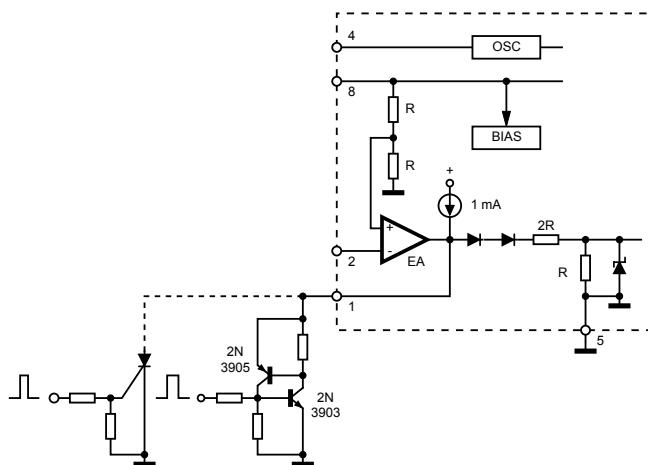
A small RC filter may be required to suppress switch transients.

Figure 20. Slope compensation techniques


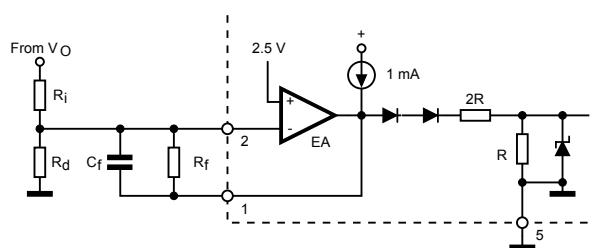
AMG110120170920MT

Figure 21. Isolated MOSFET drive and current transformer sensing


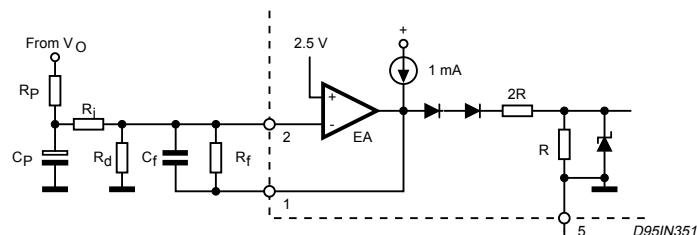
AMG110120170921MT

Figure 22. Latched shutdown

AMG110120170922MT

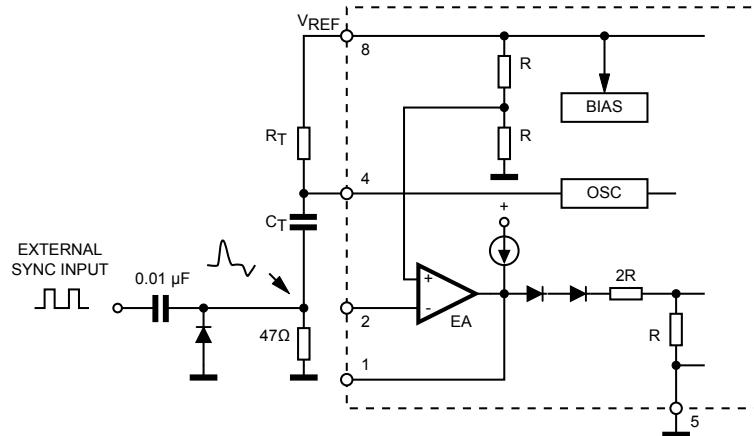
Figure 23. Error amplifier compensation

for boost and flyback converters operating with continuous inductor current.



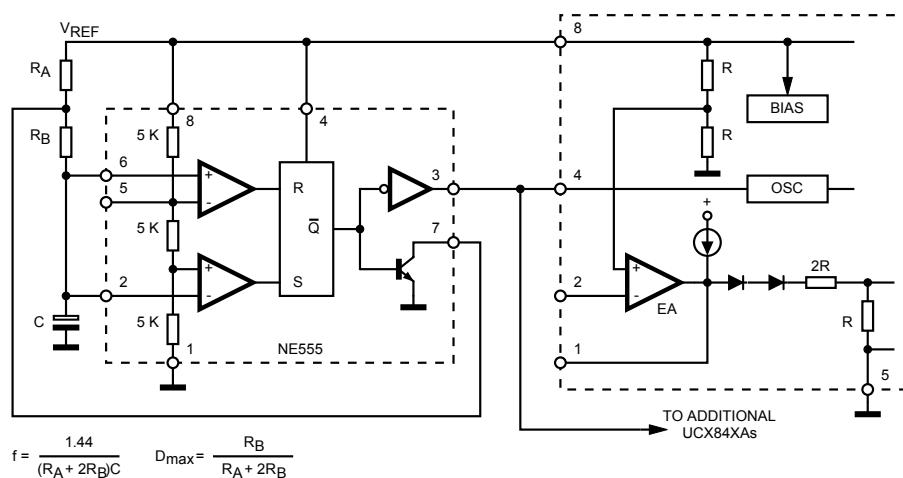
Error Amp compensation circuit for stabilizing current-mode boost and flyback topologies operating with continuous inductor current.

AMG110120170923MT

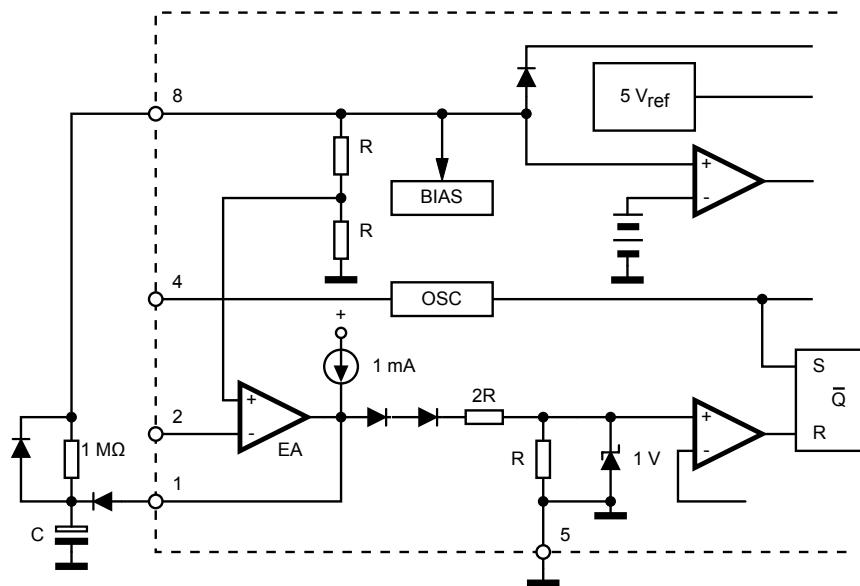
Figure 24. External clock synchronization


The diode clamp is required if the Sync amplitude is large enough to cause the bottom side of C_T to go more than 300 mV below ground.

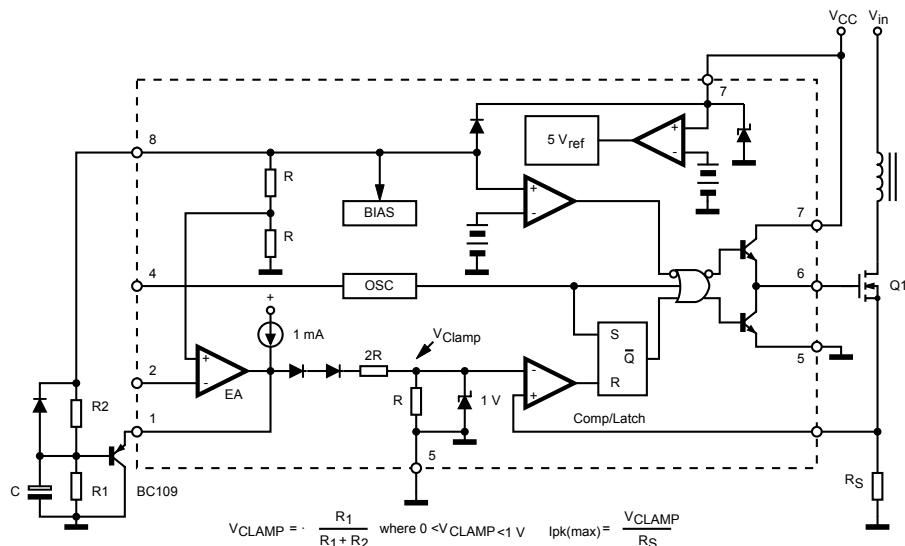
AMG110120170924MT

Figure 25. External duty cycle clamp and multi unit synchronization


AMG110120170925MT

Figure 26. Soft-start circuit


AMG110120170926MT

Figure 27. Soft-start and error amplifier output duty cycle clamp


AMG110120170927MT

9.1.2 Documentation

Each product shipment includes a set of associated documentation within the shipment box. This documentation depends on the quality level of the products, as detailed in the table below.

The documentation is provided on printed paper in a dedicated envelop.

Table 11. Default documentation provided with the parts

Quality level	Documentation ⁽¹⁾
Engineering model	Certificate of conformance including: <ul style="list-style-type: none">• Customer name• Customer purchase order number• ST sales order number and item• ST part number• Quantity delivered• Date code• Reference datasheet• Reference to the TN1180 on engineering models• ST Rennes assembly lot ID
ESCC flight	Certificate of conformance including: <ul style="list-style-type: none">• Customer name• Customer purchase order number• ST sales order number and item• ST part number• Quantity delivered• Date code• Serial numbers• Reference of the applicable ESCC qualification maintenance lot• Reference to the ESCC detail specification• ST Rennes assembly lot ID Radiation verification test report ⁽²⁾

1. Default documentation only. Contact STMicroelectronics sales office for optional documentation.
2. Report of the ESCC22900 test supporting the delivered parts

Revision history

Table 12. Document revision history

Date	Revision	Changes
12-Sep-2011	1	First revision
21-Mar-2017	2	Updated the features, the description and Table 1: "Device summary" in cover page. Updated Table 2: "Absolute maximum ratings", Figure 2: "Pin connection", Table 5: "Electrical characteristics ", Figure 3: "Unbias conditions", Table 7: "Electrical parameter during irradiation testing", Section 6.1.3: "Heavy Ions" and Table 10: "Order codes". Added Section 9.1: "Other information". Minor text changes.
04-Aug-2017	3	Updated Table 5: "Electrical characteristics ", Figure 3: "Unbias conditions", Figure 19: "Undervoltage lockout" and Figure 21: "Slope compensation techniques". Minor text changes.
24-Apr-2019	4	Updated Table 5. Total dose performance and Table 9. Order codes.
19-May-2020	5	Updated the cover page. Updated Table 2. Thermal data, Table 4. Electrical characteristics , Table 5. Total dose performance, Table 1, Table 9. Order codes and Table 11. Default documentation provided with the parts.
11-Jun-2020	6	Updated package silhouette on the cover page.

Contents

1	Block diagram	2
2	Maximum ratings	3
3	Thermal data	4
4	Pin connection	5
5	Electrical characteristics.....	6
6	Radiation characteristics	8
6.1	Total dose.....	8
6.2	Single event effect.....	11
7	Test circuit	12
8	Package information.....	20
8.1	Flat-8 package information.....	20
9	Ordering information	21
9.1	Other information.....	21
9.1.1	Traceability information.....	21
9.1.2	Documentation	22
	Revision history	23

List of tables

Table 1.	Absolute maximum ratings	3
Table 2.	Thermal data.	4
Table 3.	Pin functions	5
Table 4.	Electrical characteristics	6
Table 5.	Total dose performance	8
Table 6.	Post radiation electrical characteristics	9
Table 7.	Radiation hardness assurance summary.	11
Table 8.	Flat-8 mechanical data	20
Table 9.	Order codes	21
Table 10.	Date codes	21
Table 11.	Default documentation provided with the parts.	22
Table 12.	Document revision history.	23

List of figures

Figure 1.	Block diagram (toggle flip-flop used in the ST1845 only)	2
Figure 2.	Pin connection	5
Figure 3.	Open loop test circuit	12
Figure 4.	Timing resistor vs oscillator frequency	12
Figure 5.	Output dead-time vs oscillator frequency	12
Figure 6.	Oscillator discharge current vs temperature	13
Figure 7.	Maximum output duty cycle vs timing resistor	13
Figure 8.	Error amp open-loop gain and phase vs frequency	13
Figure 9.	Current sense input threshold vs error amp output voltage	13
Figure 10.	Reference voltage change vs source current	14
Figure 11.	Reference short-circuit current vs temperature	14
Figure 12.	Output saturation voltage vs load current	14
Figure 13.	Supply current vs supply voltage	14
Figure 14.	Output waveform	14
Figure 15.	Output cross conduction	14
Figure 16.	Oscillator and output waveforms	15
Figure 17.	Error amp configuration	15
Figure 18.	Undervoltage lockout	15
Figure 19.	Current sense circuit	16
Figure 20.	Slope compensation techniques	16
Figure 21.	Isolated MOSFET drive and current transformer sensing	16
Figure 22.	Latched shutdown	17
Figure 23.	Error amplifier compensation	17
Figure 24.	External clock synchronization	18
Figure 25.	External duty cycle clamp and multi unit synchronization	18
Figure 26.	Soft-start circuit	19
Figure 27.	Soft-start and error amplifier output duty cycle clamp	19
Figure 28.	Flat-8 package outline	20

IMPORTANT NOTICE – PLEASE READ CAREFULLY

STMicroelectronics NV and its subsidiaries ("ST") reserve the right to make changes, corrections, enhancements, modifications, and improvements to ST products and/or to this document at any time without notice. Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST's terms and conditions of sale in place at the time of order acknowledgement.

Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers' products.

No license, express or implied, to any intellectual property right is granted by ST herein.

Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

ST and the ST logo are trademarks of ST. For additional information about ST trademarks, please refer to www.st.com/trademarks. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously supplied in any prior versions of this document.

© 2020 STMicroelectronics – All rights reserved